



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STW9NK90Z	TSLW*EZ9K6WF	A	Z8GA	2015-09-18
Amount		UoM	Unit type	ST ECOPACK Grade
4430.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.75X20.15X5.15	3	Through-hole	
Comment	Package: TO 247			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSLW*E29K6WF					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	21.690	mg	supplier	die	Silicon (Si)	7440-21-3		19.121	mg	881553	4316
				supplier	metallization	Aluminium (Al)	7429-90-5		2.198	mg	101342	496
				supplier	Passivation	Silicon Oxide	7631-86-9		0.186	mg	8576	42
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.009	mg	415	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.130	mg	5994	29
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.046	mg	2121	10
Leadframe	Copper & its alloys	2754.863	mg	supplier	alloy	Copper (Cu)	7440-50-8		2739.272	mg	994341	618346
				supplier	alloy	Iron (Fe)	7439-89-6		1.261	mg	458	285
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.304	mg	836	520
				supplier	metallization	Nickel (Ni)	7440-02-0		11.952	mg	4339	2698
				supplier	metallization	Phosphorus (P)	12185-10-3		0.074	mg	27	17
Soft Solder	Other Organic Materials	10.236	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.775	mg	954963	2207
				supplier	solder	Silver (Ag)	7440-22-4		0.256	mg	25010	58
				supplier	solder	Tin (Sn)	7440-31-5		0.205	mg	20027	46
Bonding wires	Other inorganic materials	2.712	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.712	mg	1000000	612
				supplier	mold compound	Silica, vitreous	60676-86-0		1421.852	mg	870001	320960
				supplier	mold compound	Epoxy resin	Proprietary		163.431	mg	100000	36892
				supplier	mold compound	Phenol resin	Proprietary		40.857	mg	25000	9223
Encapsulation	Other Organic Materials	1634.311	mg	supplier	mold compound	Carbon Black	1333-86-4		8.171	mg	5000	1844
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.188	mg	1000000	1397
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.188	mg	1000000	1397